DANPUR® R80

DESCRIPTION

DANPUR® R80 is a reactive hot melt based on polyurethane. It deals with a hot melt adjustment a very high viscosity resistance for laminations on absorbent or coarse meshed textile carrier at which the reactive hot melt should not penetrate so deep into the fabrics during the application. Due to the chemical composition is this reactive hot melt very suitable for textile laminations, laminations, laminations of plastic foils like PVC, TPU ABS with textiles. Furthermore, the product is very suitable for the lamination of textiles on different carrier materials like wood, mineral materials and other composite materials.

PHYSICAL PARAMETER

	Values	Method
Solids	100 %	
Brookfield Viscosity (100 °C)	22.500 +/- 2.500 mPa.s.	Brookfield
Brookfield Viscosity (120 °C)	6.750 +/- 1.350 mPa.s	Brookfield
Appearance	Opaque to slightly yellowish.	

APPLICATION PARAMETER

	Values	Method
Processing temperature	100 – 110 °C	
Application temperature on textile carrier	Depending on the kind of application 80 – 130 °C	
Application weight	6,0 - 20,0 g/m² (Up to 40 g/m², depending on the substrate)	
Open time	Medium	

APPLICATION

- This reactive hot melt is characterized by a medium to high viscosity, whereby the processing is possible at low application temperatures.
- Especially adjusted for textile laminations, at which the reactive hot melt adhesive film shall not penetrate so heavy into the fabrics and remains on the top at the warm application.
- Especially designed to achieve a high cure.
- Suitable for standard laminations, fabrics and non-woven fabrics, foams, polyester and PU-films and membrane as well as PVC.
- Developed for high processing and lamination speeds.
- Optimal washing resistance at high temperatures.
- Optimal resistance at dry cleaning.

PROCESSING

The reactive hot melt DANPUR® R80 has to be processed with an applicator, which is suitable for the processing of reactive hot melts. For the processing, these processing plants shall work by melt container or by melt drum plants. This reactive hot melt can be applied on the substrates by classic applications like knife coating, dot application, screen printing or via roto gravure systems. The adhesive films of DANPUR® R80 are characterized by fast crystallization and by a high initial strength at the lamination. A high adhesion is already achieved after the lamination and within 24 hours. The end strengths are given after some days, normally after 36 hours.

COMPATIBILITY

DANPUR® R80 is an application ready reactive hot melt. No mixings with other reactive hot melts or additives should occur.

CLEANING

If the adhesive applicator remains more than 24 hours unused, the nozzle and the head of the applicator should be lubricated with mineral grease. Thus, it is prevented that that the product is crosslinked by air humidity. If the adhesive applicator remains more than 2 days unused, all systems (nozzles, the applicator head, tubes, melt bath) should be cleaned with 1-2 kg TPU cleaner. Flush the system so long until the product, which comes out of the nozzle, is 100 % TPU cleaner. In order to reactivate the adhesive again, it is necessary to repeat the procedure in reverse order and to flush the system so long in order that the product which comes from the nozzle is 100 % DANPUR® R80, without blue color. The temperature should not be higher than 130 °C.

STORAGE

DANPUR® R80 can be stored twelve months at 0 to +25 °C in original unopened containers kept from becoming exposed to the weather inside dry premises. Opened container must be used up in as short a time as possible.

PRODUCT SAFETY

When using PUR adhesives, it is important to avoid skin contact. It is recommended to wear gloves you must take the normal precautions for handling isocyanates.

*See the safety data sheet for further information.

PACKAGING

18 kg container, or 50 kg container, or 200 kg container.

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